

SLIM SMD INDUCTOR - ETPRH2D14 SERIES



•FEATURE

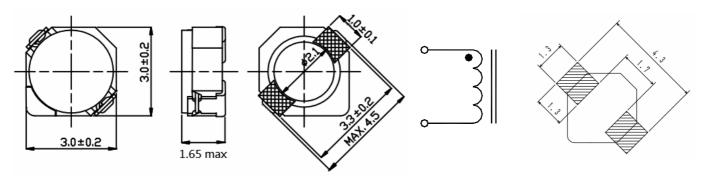
- 1. Low profile and small size (Height: 1.65mm Max)
- 2. Low DC resistance
- 3. Magnetic Shielding type

Applications

- 1. LCD panels
- 2. Digital camera
- 3. PDA and others portable

Shape and Dimension

Schematics and Land Patterns(mm)



Specification

Part Number	L(uH)	DCR(ΩMax)	IDC(A)(Max)
ETPRH2D14-2R2N	2.2±30%	0.094	1.50
ETPRH2D14-3R3N	3.3±30%	0.130	1.10
ETPRH2D14-4R7N	4.7±30%	0.169	1.00
ETPRH2D14-6R8N	6.8±30%	0.213	0.85
ETPRH2D14-100N	10±30%	0.294	0.70
ETPRH2D14-220N	22±30%	0.774	0.42
ETPRH2D14-330N	33±30%	1.200	0.40

Note1. Measurement frequency of Inductance value: at 100KHz, 1V

Note2. Measurement ambient temperature of L, DCR and IDC : at 25° C

Note3. The rated current indicates the current when the inductance decreases to 65% over of it's nominal value or D.C. current when the temperature rising $\Delta t=30^{\circ}$ C lower, whichever is lower

Note4. Inductance tolerance: N: ±30%

Note5. Packaging: Taping; Quantity: 3000 Pieces/reel

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GENERAL CHARACTERISTICS

- 1. Operating temperature range: -40 TO + 105°C (Includes temperature when the coil is heated)
- 2. External appearance: On visual inspection, the coil has no external defects.
- Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Y withstanding at below conditions.

Terminal should not peel off. (refer to figure at right) 5. 0N 60 sec.

- 4. Insulating resistance: Over $100M\Omega$ at 100V D.C. between coil and core.
- 5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core.
- 6. Temperature characteristics: Inductance coefficient (0~2,000)x10-6/°C (-25~+80°C).
- 7. Humidity characteristics(Moisture Resistance): Inductance deviation within ±5%, after 96 hours in 90~95% relative humidity at 40 ±2°C and 1 hour drying under normal condition.
- 8. Vibration resistance: Inductance deviation within ±5%, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
- 9. Shock resistance: Inductance deviation within ±5%, after being dropped once with 981m/s2 (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
- 10. Resistance to Soldering Heat: 260°C, 10 seconds(See attached recommend reflow)
- 11. Storage environment: Storage condition: Temperature Range: $10^{\circ}\text{C} \sim 35^{\circ}\text{C}$ (Generally: $21^{\circ}\text{C} \sim 31^{\circ}\text{C}$) , Humidity Range: $50\% \sim 80\%$ RH (Generally: $65\% \sim 75\%$); Transportation condition: Temperature Range: $-35^{\circ}\text{C} \sim 85^{\circ}\text{C}$, Humidity Range: $50\% \sim 95\%$ RH
- 12. Use components within 12 months. If 12 months or more have elapsed, check solderability before use.
- 13. Reflow profile recommend:

Lead-free heat endurance test

Lead-free the recommended reflow condition

